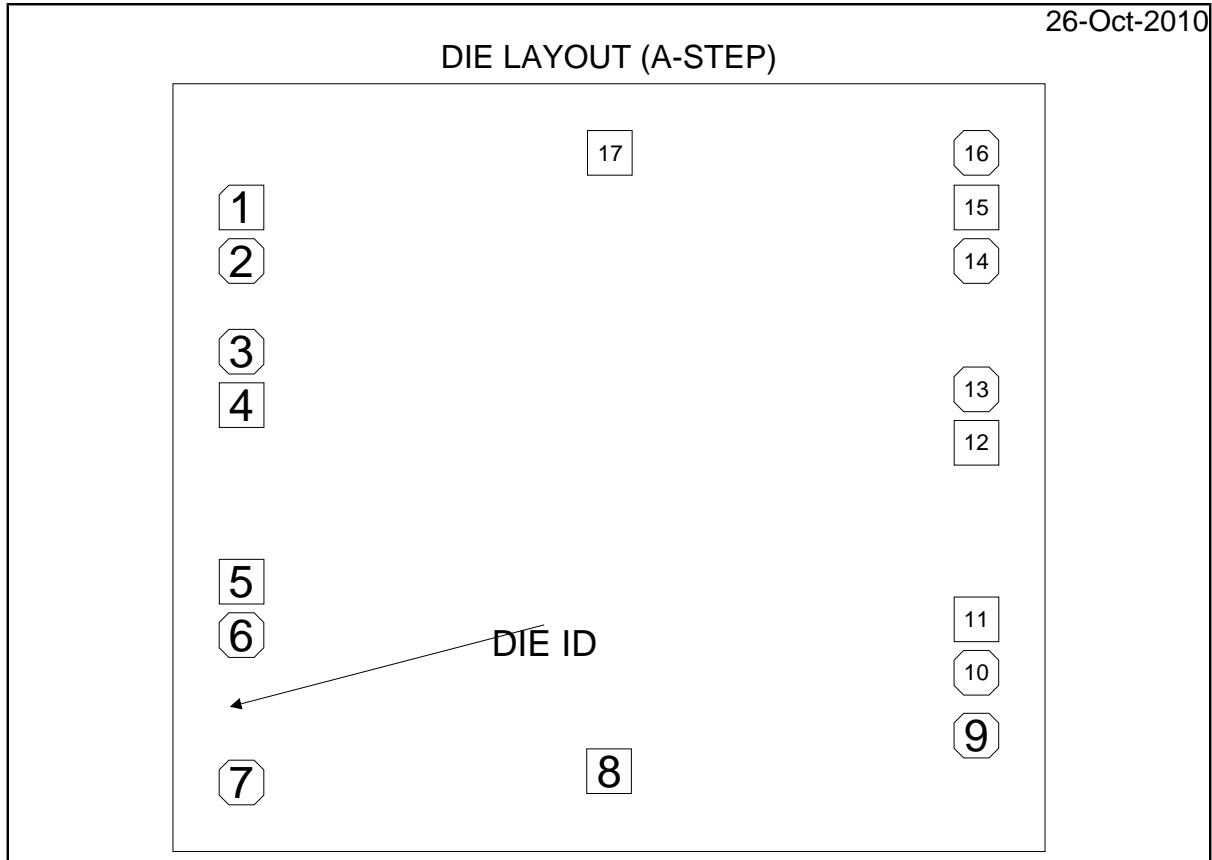


LMP7702 MDA  
Precision Dual Op Amp



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LMP7702A	Bond Pad Opening Size (min)	75.00µm x 75.00µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDON NITRIDE
Wafer Diameter	203.2mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1465.58µm x 1290.32µm 57.7mils x 50.8mils	Back Side Connection	Floating
Thickness	0.0µm Nominal		
Min Pitch	296.70µm		

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

LMP7702 MDA  
Precision Dual Op Amp

Die Bond Pad Coordinate Locations(A-Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used						
Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X	Y	
OUTPUT	1	-367.90	333.50	75.00	x	75.00
V-	2	-367.90	-56.25	75.00	x	75.00
V+	3	-367.90	-259.20	75.00	x	75.00
-IN	4	397.20	-368.10	75.00	x	75.00
NC	5	394.90	11.75	75.00	x	75.00
+IN	6	398.60	368.65	75.00	x	75.00
OUT A	1	-617.60	437.25	75.00	x	75.00
NC	2	-617.60	347.25	75.00	x	75.00
NC	3	-617.60	194.90	75.00	x	75.00
IN A-	4	-617.40	105.10	75.00	x	75.00
IN A+	5	-617.40	-191.60	75.00	x	75.00
NC	6	-617.60	-281.40	75.00	x	75.00
NC	7	-617.60	-529.10	75.00	x	75.00
V-	8	0.10	-510.10	75.00	x	75.00
NC	9	617.40	-450.30	75.00	x	75.00
NC	10	617.40	-344.70	75.00	x	75.00
IN B+	11	617.60	-254.90	75.00	x	75.00
IN B-	12	617.60	41.80	75.00	x	75.00
NC	13	617.40	131.60	75.00	x	75.00
NC	14	617.40	347.25	75.00	x	75.00
OUT B	15	617.60	437.25	75.00	x	75.00
NC	16	617.40	529.05	75.00	x	75.00
V+	17	1.40	529.05	75.00	x	75.00

LMP7702 MDA  
Precision Dual Op Amp

## Notes

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